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The document following this cover page is marked as “Cypress” document as this is the company that originally developed the product. Please note that Infineon will continue to offer the product to new and existing customers as part of the Infineon product portfolio.

**Continuity of document content**

The fact that Infineon offers the following product as part of the Infineon product portfolio does not lead to any changes to this document. Future revisions will occur when appropriate, and any changes will be set out on the document history page.

**Continuity of ordering part numbers**

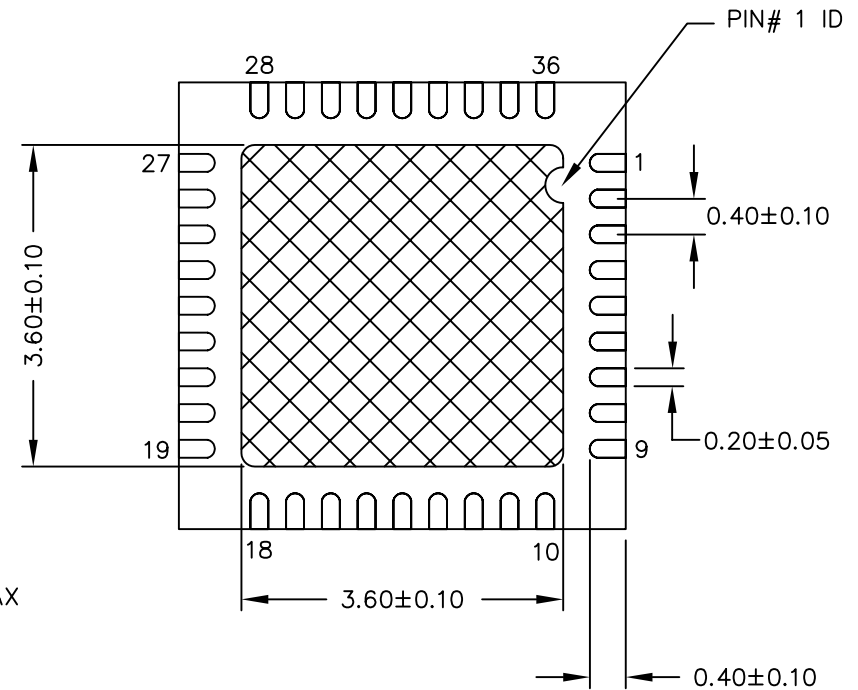
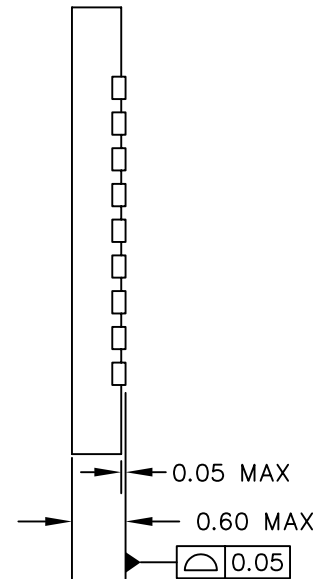
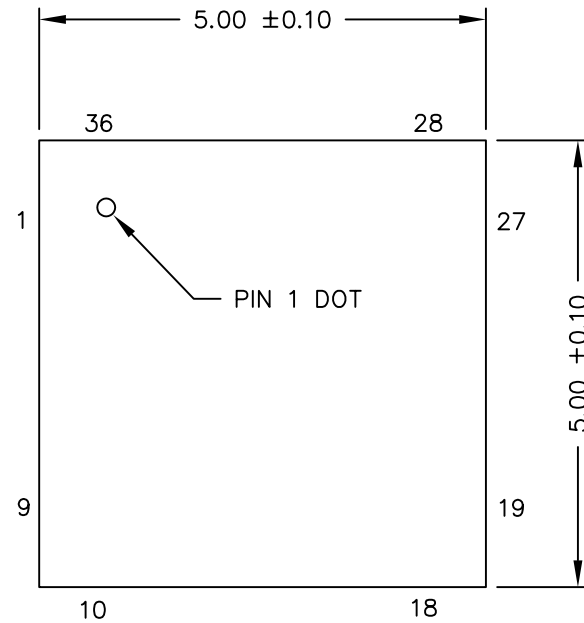
Infineon continues to support existing part numbers. Please continue to use the ordering part numbers listed in the datasheet for ordering.

REVISIONS						
PAGE	ZONE	REV	ECN	DESCRIPTION	DATE	APPROVED
1	-	**	2597612	NEW SPEC	10/29/08	JSO
1	-	*A	2661218	CORRECTED THE TOLERANCE FOR PACKAGE THICKNESS FROM +/-0.1MM TO +/-0.05MM	02/17/09	JSO
1	-	*B	2672284	CORRECTED LEAD WIDTH DIMENSION TO 0.20MM NOMINAL TO COMPLY WITH JEDEC. ADDED UNIT WEIGHT	03/11/09	JSO
1	-	*C	2725101	CORRECTED TITLE FROM 5X5X0.55 MM TO 5X5X0.60 MM. CORRECTED LEAD WIDTH TOLERANCE TO 0.05	06/22/09	JSO
1	-	*D	2820496	CHANGE TEMPLATE. CHANGE TITLE FROM QFN 36 5 X 5 X 0.60 MM PACKAGE OUTLINE 3.6X3.6 EPAD (SAWN TYPE) TO PACKAGE OUTLINE, 36L QFN 5X5X0.60 MM LQ36 3.6X3.6 EPAD (SAWN TYPE)	12/03/09	QAD
1	-	*E	2845492	CORRECTED UNIT WEIGHT	1/11/10	QAD
1	-	*F	3673270	FORMAT REVISION, PER MEMO MLA-770	7/31/12	MLA
1	-	*G	3772572	NO CHANGE	10/11/12	QAD


TOP VIEW

SIDE VIEW

BOTTOM VIEW



NOTES:

1.  HATCH AREA IS SOLDERABLE EXPOSED PAD
2. BASED ON REF JEDEC # MO-220
3. PACKAGE WEIGHT: 47 ± 5 mg
4. DIMENSIONS ARE IN MILLIMETERS

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MATERIAL

SEE NOTE

DRAWN BY

MLA

DATE

7/31/12

FINISH

SEE NOTE

APPROVED BY

BSC

DATE

7/31/12



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TITLE  
PACKAGE OUTLINE, 36L QFN 5X5X0.60 MM LQ36  
3.6X3.6 EPAD (SAWN TYPE)

SIZE	PART NO.	DWG NO	REV
A	LQ36	001-49797	*G
SCALED TO FIT		N/A	SHEET 1 OF 1